

Application Data Sheet  
Application Information

Application type:: Regular  
Subject matter:: Utility  
CD-ROM or CD-R:: None  
Number of CD disks:: None  
Number of copies of CDs:: None  
Sequence submission?::  
Computer readable form (CRF)?:: No  
Number of copies of CRF::  
Title:: THERMAL ENHANCE PACKAGE WITH  
UNIVERSAL HEAT SPREADER  
Attorney docket number:: YANG-31501EM  
Request for early publication?:: No  
Request for non-publication?:: No  
Suggested drawing figure:: 3  
Total drawing sheets:: 3  
Small entity?:: No

Applicant Information

Applicant authority type:: Inventor  
Primary citizenship country:: Taiwan, R.O.C.  
Status: Full capacity  
Given name:: Ching-Hsu  
Middle name::  
Family name:: YANG  
Name suffix::  
City of Residence:: Taichung  
State or province of residence::

Country of residence:: Taiwan, R.O.C.  
Street of mailing address:: No. 3, Lane 63, Shiangshin Rd.,  
Nantuen Chiu  
City of mailing address:: Taichung  
State or province of mailing  
address::  
Country of mailing address:: Taiwan, R.O.C.  
Postal or zip code of mailing  
address::

#### Correspondence Information

Correspondence customer number:: 23364  
Phone number:: 703-683-0500  
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E-mail address:: mail@baconthomas.com

#### Representative Information

Representative customer number:: 23364

#### Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::
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#### Foreign Priority Information

Country::	Application number::	Filing Date::	Priority claimed::
TAIWAN, R.O.C.	091132625	November 5, 2002	YES

Assignee Information

Assignee name::	Advanced Semiconductor Engineering, Inc.
Street of mailing address::	26 Chin 3rd Rd., Nantze Export Processing Zone
City of mailing address::	Kaoshiung
State or province of mailing address::	
Country of mailing address::	Taiwan, R.O.C.
Postal or zip code of mailing address::	